A plus make your production a-plus

VOICE OTP IC

aP23682 – 682sec

aP23341 – 341sec

*a*P23170 – 170sec

aP23085 - 85sec

16 PIN

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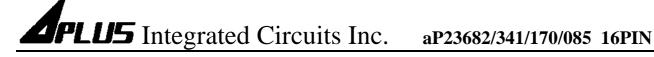
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FEATURES:

- Standard CMOS process.
- Embedded 16M/8M/4M/2M EPROM.
- 682/341/170/85 sec Voice Length at 6KHz sampling and 4-bits ADPCM compression.
- Maximum 1024 voice groups.
- Maximum 48KHz sample rate.
- Combination of voice blocks to extend playback duration.
- User selectable PCM16 or ULAW8 or PCM8 or ADPCM4 data compression.
- 6 triggering modes are available:
 - Key Mode:

S1 ~ S4 to trigger up to 9 voice groups; Power on play function.

SBT Mode:

SBT to trigger up to 1024 voice groups sequentially; Power on play function.

CPU Parallel Mode:

S[4:1] services as 4-bits address to trigger up to 16 voice groups.

with SBT goes HIGH to strobe the address bits.

SPI Mode: CSB, SCK, DI.

3 wire address control up to 1024 voice groups.

I2C Mode: SCK, DI.

2 wire address control up to 1024 voice groups.

MP3 Mode:

S1:Backward, S2: Forward, S3:Stop, S4:Reset,

SBT: Play/Pause Trigger up to 1024 voice groups.

- Voice Group Trigger Options: Edge / Level; Hold / Unholdable; Retrigger / Non-retrigger.
- Optional 16ms or 65us selectable debounce time.
- RST pin set HIGH to stop the playback at once.
- LVR (Low voltage reset).
- Programmable outputs pin out1:

for busy-H, busy-L, stop-H, stop-L, prog busy-H, prog busy-L, Loadbit,

LED flash (LED high active), ~LED flash (LED low active).

- Three kind oscillator: Internal-Rosc , External-Rosc , Crystal.
- 2V 5V single power supply and < 5uA low stand-by current.
- 16/8/4 level volume control setting available.
- 16 bits audio out.
- PWM Vout1 and Vout2 drive speaker directly.
- D/A COUT pin drives speaker through an external BJT or audio AMP.
- Development System support for voice compilation.

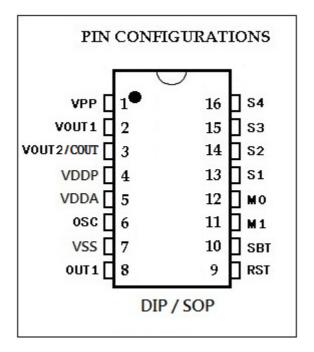
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DESCRIPTION :

aP23682/341/170/085 series high performance Voice OTP is fabricated with Standard CMOS process with embedded 16M/8M/4M/2M bits EPROM. It can store up to 682/341/170/85 sec voice message with 4-bits ADPCM compression at 6KHz sampling rate. 16-bits PCM \cdot 8-bits PCM and 8-bits ULAW at (4K to 48K sample rate) is also available for user selecting.

User selectable triggering and output signal options provide maximum flexibility to various applications. Built-in resistor controlled oscillator, 16-bits current mode DAC output and 14-bits PWM direct speaker driving output minimize the number of external components. PC controlled programmer and developing software are available.



PIN NAMES :

PIN 16-pin	Playback Mode	OTP Program Mode	Description
1	VPP	VPP	Supply ground.
2	VOUT1		PWM output to drive speaker directly.
3	VOUT2/COUT		PWM output to drive speaker directly. / DAC current output.
4	VDDP	VDDP Supply voltage.	
5	VDDA	VDDA	Analog supply voltage.
6	OSC		Oscillator input.
7	VSS	VSS	Supply ground.
8	OUT1		Programmable output (I/O pin).
9	RST	RST	Reset pin (input pin with internal pull-down).
10	SBT		Trigger pin (I/O pin with internal pull-down).
11	M1		Mode select pin 1(input with internal pull-down).
12	M0		Mode select pin 0(input with internal pull-down).
13 ~ 16	5 S1~S4	S2 · S3	Trigger pin (I/O pin with internal pull-down).

PIN DESCRIPTIONS :

$S1 \sim S4$:

Input Trigger Pins:

- In Key Mode: S1 to S4 is used to trigger 9 voice groups.
- In CPU Parallel Mode :This pin low to high [Latch] the address at S1(lsb) to S4(msb) and starts the voice playback.
- In SPI Mode:
 - S1 is Chip Select (CSB) pin to initiate the command input.
 - S2 is the Serial Clock (SCK) pin which clocks the input command and data bits into the chip.
 - S3 is the Data In (DI) pin in which command and data bits are shifted input into the chip.
- In I2C Mode:
 - S2 is the Serial Clock (SCK) pin which clocks the input command and data bits into the chip.
 - S3 is the Data In (DI) pin in which command and data bits are shifted input into the chip.
- In MP3 Mode:
 - S1:Backward. S2:Forward. S3:Stop. S4: Reset.

SBT:

Input Trigger Pin:

- In SBT Mode: This pin is trigger pin to play Voice Groups one time or looping sequentially up to 1024 Voice Groups.
- In CPU Parallel Mode: This pin is used as address strobe to latch the Voice Group address input at S1 to S4 and starts the voice playback.

- In MP3 Mode: This pin is Play / Pause.

VDDP and VDDA:

Power Supply Pins: These two pins must be connected to the positive power supply.

VSS:

Power Ground Pins: VSS and VPP pins must be connected together to the power ground during voice playback.

In Circuit Program: VSS and VPP pins must be separated to the power ground. Connect resistor between power ground and VPP.

VPP:

During voice playback, this pin and VSS must be connected together to the power ground. In Circuit Program: This pin is connected to a separate 8.5V power supply voltage for OTP programming. Connect resistor between power ground and VPP.

Note: Resistor is 10K Ω .

M0 and **M1**:

In Key Mode \ SBT Mode \ CPU Parallel Mode \ MP3 Mode \ SPI Mode \ and I2C Mode \, M0 and M1 can be used for Crystal oscillator or volume control.

VOUT1 and VOUT2:

14-bits PWM output pins which can drive speaker and buzzer directly for voice playback.

COUT:

16-bits current mode DAC output for voice playback.

OSC:

During voice playback, an external resistor is connected between this pin and the VDD pin to set the sampling frequency. Or keep OSC floating if choosing INT-Rosc.

Note: External resistor is 68K Ω .

OUT1:

OUT1 can select output function as below:

- 1. Busy- H: When voice is playing, output high level signal.
- 2. Busy- L: Inverted output of Busy- H.
- 3. LED- Flash: When voice is playing, output LED flash pulse.
- 4. ~LED- Flash: Inverted output of LED- Flash.
- 5. Stop- H: When voice plays finished, output stop pulse.
- 6. Stop- L: Inverted output of Stop- H.
- 7. LoadBit: After load voice data to buffer success, output logic high signal.
- 8. Prog-Busy H: When voice of Prog-Busy set 1, high pulse output. When voice of Prog-Busy set 0, low pulse output.
- 9. Prog-Busy L: Inverted output of Prog-Busy H.

RST:

Chip reset in playback mode.

External reset pull high a capacitor if used internal reset not. capacitor:100nF

VOICE SECTION COMBINATIONS :

Voice files created by the PC base developing system are stored in the built-in EPROM of the aP23682/341/170/085 chip as a number of fixed length Voice Blocks. Voice Blocks are then selected and grouped into Voice Groups for playback. Up to 1024 Voice Groups are allowed. A Voice Blocks Table is used to store the information of combinations of Voice Blocks and then group them together to form Voice Group.

Chip	aP23682	aP23341	aP23170	aP23085
Memory size	16M bits	8M bits	4M bits	2M bits
Max no. of Voice Block	2016	2016	2016	2016
Max. no. of Voice Group	1024	1024	1024	1024
Voice Length (@ 6KHz 4-bit ADPCM)	682 sec	341 sec	170 sec	85 sec

Example of Voice Block Combination :

Assume here we have three voice files, they are "How are You?", Sound Effect and Music. Each of the voice file is divided into a number of fixed length Voice Block and stored into the memory. Voice block:

B1 = "How"	B2 = "are"	B3 = "You"
B4 = Sound Effect	B5 = Music1	B6 = Music2

Voice Blocks are grouped together using Voice Table to form Voice Group for playback:

Group no.	Voice Group contents	Voice Table Entries
Group 1	"How are You?"	B1+B2+B3
Group 2	Sound Effect + "How are You?"	B4+ B1+B2+B3
Group 3	"How are You?" + Music1	B1+B2+B3+B5
Group 4	Music2	B6

Voice Data Compression :

Voice File data is stored in the on-chip EPROM as either 4-bits ADPCM or 8-bits PCM/ ULAW format or 16-bits PCM format. Voice data are stored as 16-bits PCM forma is without compression. The voice playback quality is best. Voice data stored as 4-bits ADPCM or 8-bits PCM/ ULAW provide 4:2 data compression to save memory space. But voice playback quality with be lower than 16-bits PCM format.

Group Options:

User selectable options that affect each individual group are called Group Options. They are:

- Edge or Level trigger.
- Unholdable or Holdable option.
- Re-triggerable or Non-retriggerable option.
- Stop pulse disable or enable.

Fig. 1 to Fig. 6 show the voice playback with different combination of triggering mode and the relationship between outputs and voice playback.

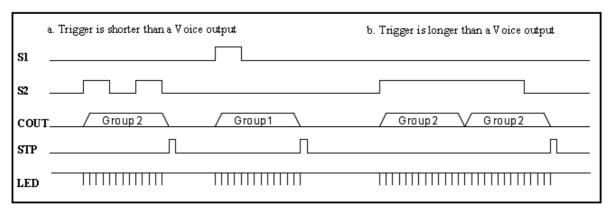


Fig. 1 Level, Unholdable, Non-retriggerable

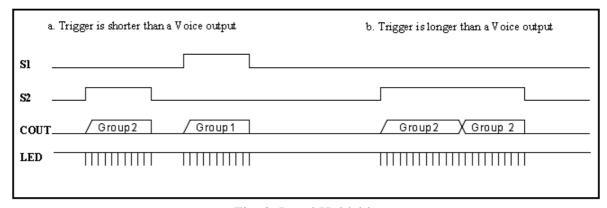


Fig. 2 Level Holdable

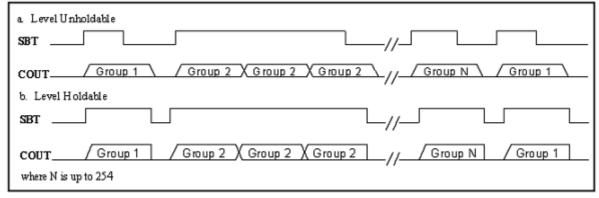


Fig. 3 SBT sequential trigger with Level Holdable and Unholdable

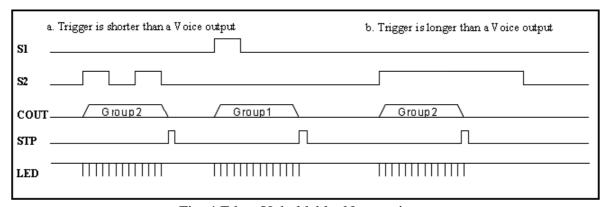


Fig. 4 Edge, Unholdable, Non-retrigger

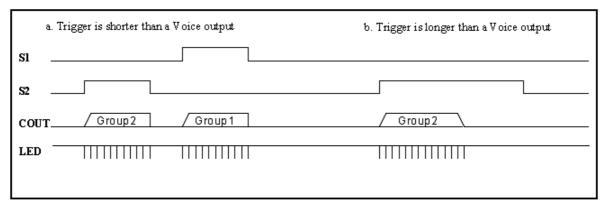


Fig. 5 Edge, Holdable

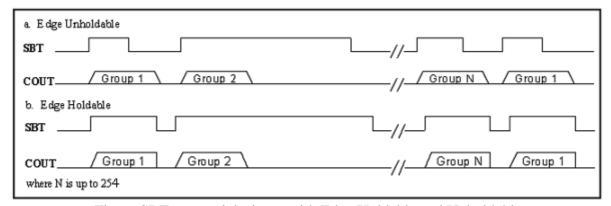


Fig. 6 SBT sequential trigger with Edge Holdable and Unholdable

• TRIGGER MODES:

There are six trigger modes available for aP23682/341/170/085 series.

- Key Mode.
- SBT Mode.
- CPU Parallel Mode.
- SPI Mode.
- I2C Mode.
- MP3 Mode.

• Key Mode:

With this trigger mode, the beginning 9 Voice Groups are triggered by setting S1 to S4 to HIGH or LOW in different combinations. Each Voice Group can have its only independent trigger options (See Fig. 1,2,4 and 5 for trigger options definition).

The setting of S1 to S4 for triggering the 1st to the 9nd Voice Groups are as follow:

Voice Group	S1	S2	S3	S4
SW1	HIGH	NC	NC	NC
SW2	NC	HIGH	NC	NC
SW3	NC	NC	HIGH	NC
SW4	NC	NC	NC	HIGH
SW5	HIGH	HIGH	NC	NC
SW6	NC	HIGH	HIGH	NC
SW7	NC	NC	HIGH	HIGH
SW8	SW8 HIGH		HIGH	NC
SW9	HIGH	HIGH	HIGH	HIGH

★★★ Note: NC represents open or no connection

• SBT Mode:

A maximum of 1024 Voice Groups are available. And can be triggered one by one sequentially with the SBT key (See Fig. 3 and 6).

• **CPU Parallel Mode:**

In this mode, S4 to S1 serve as 4-bits addresses input for 16 Voice Groups with S4 represents the MSB and S1 represents LSB. After Group address is set and ready, setting the SBT input pin LOW to HIGH will [LATCH] and trigger the corresponding Voice Group to playback.

Trigger options defined in Fig. 1,2, 4 and 5 are valid for this mode.

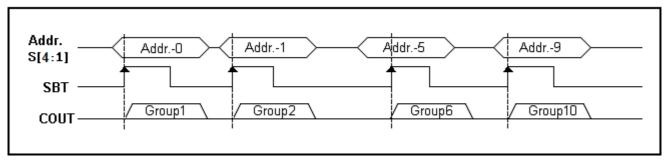


Fig. 7 CPU Parallel Trigger Mode

Note that SBT pin cannot be used as Single Button Sequential trigger in this mode (Fig. 7). For instead, it acts as a Strobe input to clock-in the Voice Group address set at S1 to S4 into the chip.

Voice Groups are represented in Binary address format. For example:

[S4:S1] = 0000 0000 (00hex) for Voice Group #1 [S4:S1] = 0000 0001 (01hex) for Voice Group #2 •••• [S4:S1] = 0000 1000 (08 hex) for Voice Group #9 •••• [S4:S1] = 0000 1111 (0F hex) for Voice Group #16

CPU Serial Command Description:

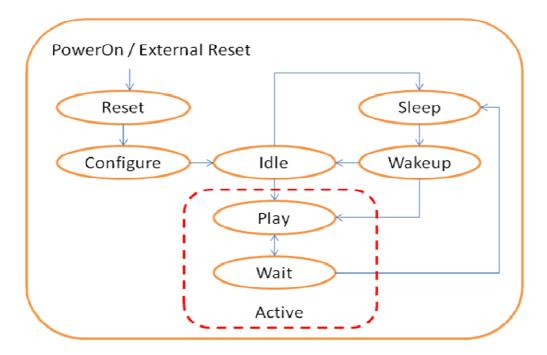
CPU Serial Command include SPI Mode · I2C Mode.

The command support to reference Fig.8 CPU Serial Command Description.

LOAD	 This command pre-load the next Voice Group Address into the address buffer. The "Full/Load" signal will become HIHG once the Group Address is loaded. The Voice Group will be played once the playing of the current Voice Group is finished. The "Full/Load" signal will become LOW once the Voice Group is played and the address buffer is released and ready for next PREFECT action. Using this command make sure there is no gap between each Voice Group. 								
PLAY	This command load the Voice Group Address into the address buffer. The current Voice Group will be stopped and play the new one.								
PU1	Power up the chip without ramp-up (suitable for PWM direct drive).								
PU2	Power up the chip with ramp-up (suitable for COUT transistor drive).								
PD1	Power down the chip without ramp-down (suitable for PWM direct drive).								
PD2	Power down the chip with ramp-down (suitable for COUT transistor drive).								
VOL	Set Volume index of volume Table.								
VOL	Decrease the volume index of volume Table.								
VOL++	Increase the volume index of volume Table.								
PAUSE	Pause the current Voice Group.								
RESUME	Resume the current Voice Group.								
REWIND	Play the current Voice Group from it's beginning.								
STOUT	Device Status Output.								

Fig. 8 CPU Serial Command Description

State Description:



State Name	Description
Reset	Include Power On Reset (typ 5us) and external reset (depends on the external reset circuit).
	All pins are input floating.
	Serial Command inhibited.
	After reset, state transfer to the "Configure "state.
Configure	Internal Chip Configuration.
	All pins are input floating.
	Serial Command inhibited. (Max configure time = 2ms)
	After configuration, state transfer to the "Idle" state.
Idle	State transfer to the "Play" state if "active command" received before timeout.
	After time out without active command, state transition to the "Sleep" State.
Play	Playing Voice Group include ramp.
	State transfer to the "Wait" state if nothing to be played.
Wait	Wait new Serial command and back to the play state without time limit.
	State transition to the "Sleep" state if "de-active command" received.
	Ramp down before transition to the sleep if the "PD2" command be accepted.
Sleep	State transition to the "Wakeup" state if selected by the host CPU.
	(Wait sleep to wake up state time = 20us.)
Wake up	Single command be buffered and wait to execute after wakeup state!!
	(Max wakeup time = 2ms).
	State transition to the "Play" state if active command received else to the "Idle" state.

Fig. 9 State Description

In CPU Serial Command Control:

- a. Using PUP1/PUP2 command first from de-active state.
 - Add 2ms delay after PUP1/PUP2 command is necessary.
- b. Max "Output Delay of Busy/Full Signal" equal 2ms during active.
- c. Output select to reference PIN DESCRIPTIONS of OUT1.

^{***} Active commands are "Load", "Play", "PU1" and "PU2". De-Active commands are "PD1" and "PD2".

• SPI Mode :

This trigger mode is specially designed for simple CPU interface. The aP23682/341/170/085 is controlled by command sent to it from the host CPU. S1 to S3 are used to input command word into the chip while OUT1 as output from the chip to the host CPU for feedback response.

- S1 acts as CSB (Chip Select) to initiate the command word input.
- S2 acts as SCK (Serial Clock) to clock-in the command word at rising edge.
- S3 acts as DI (Data-In) to input the command bits.
- OUT1 acts as BUSY to indicate the chip is in busy state(include play and ramp).
- M0 acts as volume level increase.
- M1 acts as volume level decrease.

SPI Command Table [MSB First]: Command input into the chip 16-bits data.

Command	D15	D14	D13	D12	D11	D10	D[9:0]
LOAD	1	0	0	1	0	1	Voice Group Address Number.
PLAY	1	0	0	1	1	0	Voice Group Address Number.
PU1 w/o Ramp	1	0	1	0	0	1	don't care.
PU2 with Ramp	1	0	1	0	1	0	don't care.
PD1 w/o Ramp	1	0	1	1	0	1	don't care.
PD2 with Ramp	1	0	1	1	1	0	don't care.
VOL	0	1	0	0	0	1	0 0 0 0 0 VOL[3:0]
VOL	0	1	0	0	1	0	don't care.
VOL++	0	1	0	1	0	1	don't care.
PAUSE	0	1	1	0	0	1	don't care.
RESUME	0	1	1	0	1	0	don't care.
REWIND	0	1	1	1	0	1	don't care.

Fig. 10 SPI Command Table

SPI Command Timing Diagram:

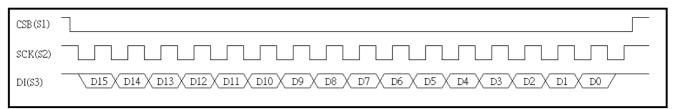


Fig.11 SPI Command timing

- * Data is latched at rising edge of SCK.
- * SPI Command function reference Fig. 8 CPU Serial Command Description.

Power up with RAMP-UP(PU2) or without RAMP-UP(PU1)

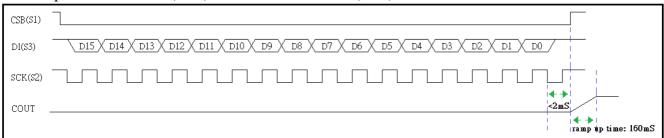


Fig. 12 Power-Up command timing

* Ramp up time: 160mS

Power down with RAMP-DOWN(PD2) or without RAMP-DOWN (PD1)

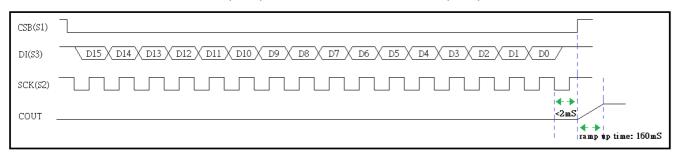


Fig. 13 Power-Down command timing

* Ramp down time: 160mS

- (1). Load Voice Group Address:
- a. Command timing reference Fig.11 SPI Command timing.
- b. D9 to D0 total 10 bits to be the Group Address.
- c. The OUT1 output (LoadBit) will become logic high once the Group Address is successfully loaded.
- d. The Load signal will become logic LOW once the Voice Group is played and the address buffer is released and ready for next Play action.
- (2). Play Voice Group Address:
- a. Command timing reference Fig.11 SPI Command timing.
- b. D9 to D0 total 10 bits to be the Group Address.
- c. Playing assign group address immediately.
- (3). Power up with RAMP-UP(PU2) or without RAMP-UP(PU1):
- a. Command timing reference Fig. 12 Power-Up command timing.
- b. PU1: will power-up the chip and set the VOUT to center value immediately and stay there.
- c. PU2: will power-up the chip and ramp-up COUT from bottom to center value and stay there.
- (4). Power-down with RAMP-DOWN(PD2) or without RAMP-DOWN (PD1):
- a. Command timing reference Fig. 13 Power-Down command timing.
- b. PDN1 will power-down the chip and set the VOUT data to bottom value immediately. PDN1 will be executed correctly only if PU1 is executed before.
- c. PDN2 will power-down the chip and ramp-down the COUT from its current to bottom value. PDN2 will be executed correctly only if PU2 is executed before.
- (5). Volume Set (VOL[3:0]):
- a. Command timing reference Fig.11 SPI Command timing.
- b. D3 to D0 total 4bits($0 \sim 15$) set volume level (max : 0, min : 15)
- (6). Volume - (VOL--):
- a. Command timing reference Fig.11 SPI Command timing.
- b. Set volume level decrease.
- (7). Volume + + (VOL++):
- a. Command timing reference Fig.11 SPI Command timing.
- b. Set volume level increase.
- (8). Pause and Resume (PAUSE; RESUME):
- a. Command timing reference Fig.11 SPI Command timing.
- b. In Pause state, VOUT1 and VOUT2 will stay at logic LOW while the COUT will stay at the current D/A data level. When Resume, the COUT data will continue at the current D/A data level.
- (9). Rewind:
- a. Command timing reference Fig.11 SPI Command timing.
- b. Play the current Voice Group from it is beginning.

I2C Mode:

This trigger mode is specially designed for simple CPU interface. The aP23682/341/170/085 is controlled by command sent to it from the host CPU. S2 and S3 are used to input command word into the chip while OUT1 as output from the chip to the host CPU for feedback response.

- S2 acts as SCK (Serial Clock) to clock-in the command word at rising edge.
- S3 acts as DI (Data-In) to input the command bits.
- OUT1 acts as BUSY to indicate the chip is in busy state(include play and ramp).
- M0 acts as volume level increase.
- M1 acts as volume level decrease.

I2C Command Table [MSB First]: Command input into the chip 16-bits data.

Command	D15	D14	D13	D12	D11	D10	D[9:0]
LOAD	1	0	0	1	0	1	Voice Group Address Number.
PLAY	1	0	0	1	1	0	Voice Group Address Number.
PU1 w/o Ramp	1	0	1	0	0	1	don't care.
PU2 with Ramp	1	0	1	0	1	0	don't care.
PD1 w/o Ramp	1	0	1	1	0	1	don't care.
PD2 with Ramp	1	0	1	1	1	0	don't care.
VOL	0	1	0	0	0	1	0 0 0 0 0 VOL[3:0]
VOL	0	1	0	0	1	0	don't care.
VOL++	0	1	0	1	0	1	don't care.
PAUSE	0	1	1	0	0	1	don't care.
RESUME	0	1	1	0	1	0	don't care.
REWIND	0	1	1	1	0	1	don't care.

Fig. 14 I2C Command Table

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I2C Command Timing Diagram:

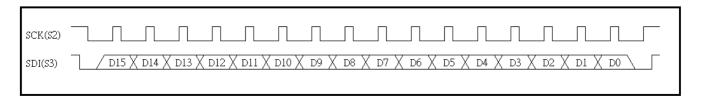


Fig.15 I2C Command timing

- * The data bit only can be changed in SCK low level, but it has to be latched before rising edge of SCK.
- * I2C Command function reference Fig. 8 CPU Serial Command Description.

Power up with RAMP-UP(PU2) or without RAMP-UP(PU1)

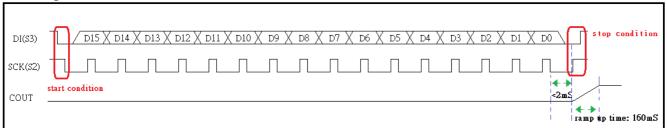


Fig. 16 Power-Up command timing

* Ramp up time: 160mS

Add stop condition after power on and internal chip configuration time finish. In Power up command: After start condition signal, add delay time more than 300us to wake up device.

Power-down with RAMP-DOWN(PD2) or without RAMP-DOWN (PD1)

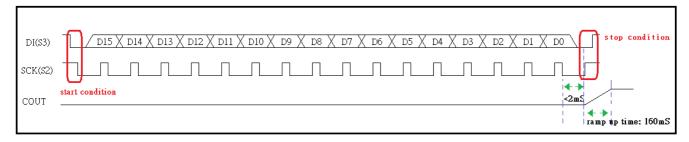


Fig. 17 Power-Down command timing

* Ramp down time: 160mS

- (1). Load Voice Group Address:
- a. Command timing reference Fig.15 I2C Command timing.
- b. D9 to D0 total 10 bits to be the Group Address.
- c. The OUT1 output (LoadBit) will become logic high once the Group Address is successfully loaded.
- d. The Load signal will become logic LOW once the Voice Group is played and the address buffer is released and ready for next Play action.
- (2). Play Voice Group Address:
- a. Command timing reference Fig.15 I2C Command timing.
- b. D9 to D0 total 10 bits to be the Group Address.
- c. Playing assign group address immediately.
- (3). Power up with RAMP-UP(PU2) or without RAMP-UP(PU1):
- a. Command timing reference Fig. 16 Power-Up command timing.
- b. PU1: will power-up the chip and set the VOUT to center value immediately and stay there.
- c. PU2: will power-up the chip and ramp-up COUT from bottom to center value and stay there.
- (4). Power-down with RAMP-DOWN(PD2) or without RAMP-DOWN (PD1):
- a. Command timing reference Fig. 17 Power-Down command timing.
- b. PDN1 will power-down the chip and set the VOUT data to bottom value immediately. PDN1 will be executed correctly only if PU1 is executed before.
- c. PDN2 will power-down the chip and ramp-down the COUT from its current to bottom value. PDN2 will be executed correctly only if PU2 is executed before.
- (5). Volume Set (VOL[3:0]):
- a. Command timing reference Fig.15 I2C Command timing.
- b. D3 to D0 total 4bits($0 \sim 15$) set volume level (max : 0, min : 15)
- (6). Volume - (VOL--):
- a. Command timing reference Fig.15 I2C Command timing.
- b. Set volume level decrease.
- (7). Volume + + (VOL++):
- a. Command timing reference Fig.15 I2C Command timing.
- b. Set volume level increase.
- (8). Pause and Resume (PAUSE; RESUME):
- a. Command timing reference Fig.15 I2C Command timing.
- b. In Pause state, VOUT1 and VOUT2 will stay at logic LOW while the COUT will stay at the current D/A data level. When Resume, the COUT data will continue at the current D/A data level.
- (9). Rewind:
- a. Command timing reference Fig.15 I2C Command timing.
- b. Play the current Voice Group from it is beginning.

• MP3 Mode:

This trigger mode is specially designed for simple MP3 function.

User can start to Play or Pause the voice by SBT pin, and Backward or Forward play by S1 pin or S2 pin, up to 1024 Voice Sections.

- SBT acts as play / pause.
- S1 acts as backward.
- S2 act as forward.
- S3 acts as stop.
- S4 act as reset.
- M0 acts as volume level increase.
- M1 acts as volume level decrease.

Option:

SPI Mode and I2C Mode are Pin S4 as data output (DO)using. DO (Pin S4) as output from the chip to the host CPU for feedback response.

DO(Pin S4) Output the status bits:

Status	Description						
S [15:9]	Reserved.						
S [8]	STO_TAG.						
S [7]	STO_BUSYB.						
S [6]	STO_FULLB / STO_EMPTY.						
S [5]	Reserved.						
S [4]	Reserved.						
S [3]	Reserved.						
S [2]	STO_VALIDB.						
S [1]	STO_PARITY.						
S [0]	STO_TAG.						

Fig. 18 SPI Output Status Table

S [15:9]: Reserved.

S [8]: STO_TAG: When received valid command the bit toggle.

S [7]: STO_BUSYB: When voice is playing the bit indicate 0 otherwise 1.

S [6]: STO_FULLB/STO_EMPTY: If voice group is waiting to be played, the bit indicate 0 otherwise 1.

S [5:3]: Reserved.

S [2]: STO_VALIDB: If the last serial command is valid the bit indicate 0 otherwise 1.

S [1]: STO_PARITY: If digit 1 in group address[D9~D0] total are odd numbers, the bit indicate 0 otherwise 1.

S [0]: STO_TAG: When received valid command the bit toggle.

SPI Mode:

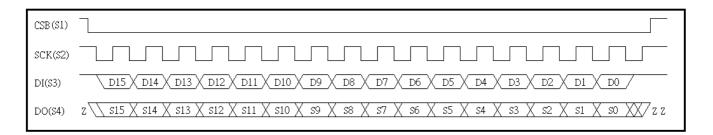


Fig. 19 SPI Data Output Command timing

SPI TIMING WAVEFORMS

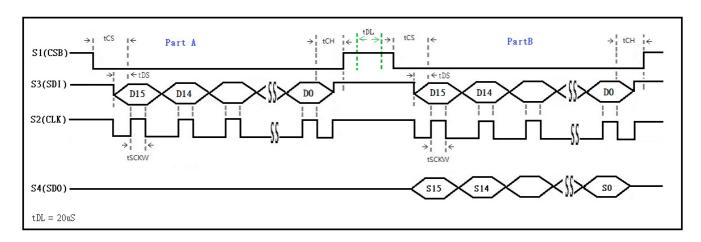


Fig. 20

Part A: Using command reference Fig. 10 SPI Command Table.

Part B: Using command is STOUT.

STOUT Command [MSB First]: Command input into the chip 16-bits data.

Command	D15	D14	D13	D12	D11	D10	D[9:0]
STOUT	0	1	1	1	1	0	don't care.

(1). STOUT(Status Out):

- a. Command timing reference Fig. 19 SPI Data Output Command timing.
- b. Get Device Status.

^{*} Data output to be changed at falling edge of SCK.

I2C Mode:

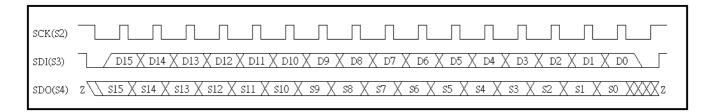


Fig. 21 I2C Data Output Command timing

I2C TIMING WAVEFORMS

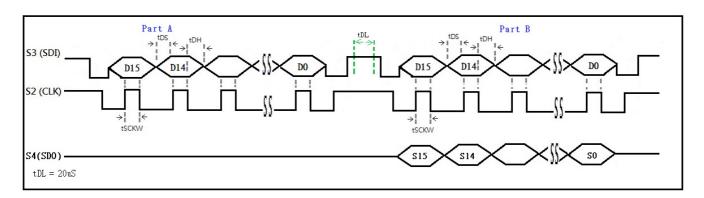


Fig. 22

Part A: Using command reference Fig. 14 I2C Command Table.

Part B: Using command is STOUT.

STOUT Command [MSB First]: Command input into the chip 16-bits data.

Command	D15	D14	D13	D12	D11	D10	D[9:0]
STOUT	1	1	1	1	1	1	don't care.

(1). STOUT(Status Out):

- a. Command timing reference Fig. 21 I2C Data Output Command timing.
- b. Get Device Status.

^{*} Data output to be changed at falling edge of SCK.

Oscillator Resistance:

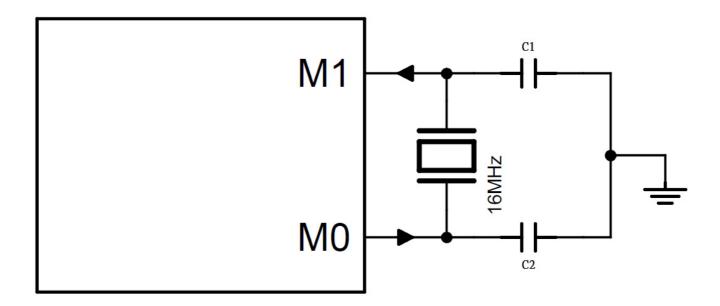
We have 3 modes can choose: Internal resistor . External resistor . Crystal resistance.

Rosc Int – No need to add resistor for OSC.

Rosc Ext – Use 68K ohm resistor in OSC pin.

XT - Setting Crystal mode in M0 pin and M1 pin.

- 1. The crystal use 16MHz.
- 2. Use C1, C2 for capacitor depend on Crystal spec.



BLOCK DIAGRAM:

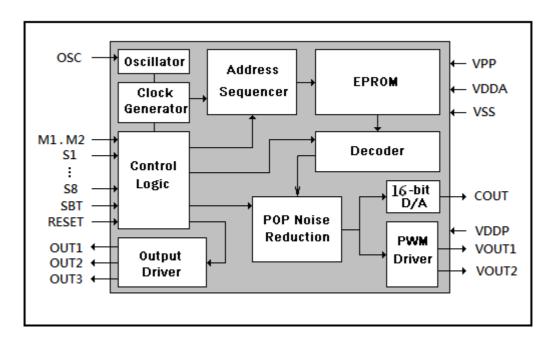


Fig. 23 Block Diagram

ABSOLUTE MAXIMUM RATINGS:

Symbol	Rating	Unit	
V _{DD} - V _{SS}	-0.5 ~ +5.0	V	
V _{IN}	$V_{SS} - 0.3 < V_{IN} < V_{DD} + 0.3$	V	
V _{OUT}	$V_{SS} < V_{OUT} < V_{DD}$	V	
T (Operating):	-10 ~ +85	$^{\circ}\!\mathbb{C}$	
T (Junction)	-10 ~ +85	$^{\circ}\!\mathbb{C}$	
T (Storage)	-10 ~ +85	$^{\circ}$	

DC CHARACTERISTICS (T_A = 0 to 70°C)₄

Symbol∂	Parameter@	Min.₽	Typ.₽	Max.₽	Unit₽	Condition	-₽
VDD_{\wp}	Operating Voltage	2.0₽	ē	5.0₽	\mathbf{V}_{\emptyset}	₽	-₽
ΔFc/Fc₽	Chip to chip frequency variation	-1.5₽	ę.	+1.5₽	%₁	₽	٠,

			₽				·
Symbol	Parameter@	\mathbf{VDD}_{e^2}	Min.₽	Typ.	Max.₽	Unit₽	Condition₽
т	C4 11 4	3.3₽	ę.	φ	1.0₽	A	ę.
IsB₽	Standby current	4.5₽	٠	φ	1.0₽	$\mathbf{u}\mathbf{A}_{^{\wp}}$	٠
T	0	3.3₽	٩	11₽	ė.	A	47
Iop₽	Operating current	4.5₽	٩	18₽	ø	mA₽	47
T	Input augment	3.3₽	4	7₽	ę.	33 A	V _{IL} =3.3V _€
Іін₽	Input current∂	4.5₽	₽	17₽	e.	$\underline{\mathbf{u}}\underline{\mathbf{A}}_{^{\wp}}$	V _{IL} =4.5V _€
$ m V_{IH^{\scriptscriptstyle ar{\circ}}}$	Input high valtage.	3.3₽	₽	2/2 V/DD .	Đ	V.	47
VIH₽	Input high voltage	4.5₽	₽	2/3 VDD¢	ø	V÷	47
V	Input low voltage. □	3.3₽	₽	1/3 VDD¢	Đ.	V _e	47
VIL.º Inpu	input fow voltages	4.5₽	₽	1/3 VDD∉	ø	V	₽
Іон₽	Output high ourrant	3.3₽	₽	-16₽	P	mA₄	Vон=2.0V ₄
IOH₽	Output high current	4.5₽	4	-25₽	ė	IIIA₽	VoH=3.5V₽
Tor.	Output law augrent	3.3₽	φ.	26₽	ø	m A a	Vol=1.0V
IoL Output 1	Output low current	4.5₽	₽	36₽	ė	mA₽	V0L-1.0 V₽
Ivout₀ VOUT	VOUT Current	3.3₽	ę.	150₽	ø	mA₊	Load=8Ω₽
	VOOT Currents	4.5₽	ę.	220₽	47	IIIA+	Load-852¢
Icout₽	COUT Current	3.3₽	ę.	4₽	ø	mA₊	Vcout=1.0V _↔
100014	COOT Current	4.5₽	ę.	4₽	ø	III/ X ⊕	full scale₽
AE/E	Frequency Stability	3.3₽	ę.	1.5₽	e e	%₽	Note1₽
$\Delta F/F_{e}$	Frequency stability	4.5₽	4	1.5₽	ø	70↔	Note2₽

Note1:

Fosc(3.3) - Fosc(2.7)

Fosc (3.3)

Note2:

Fosc(5.0) - Fosc(4.5)

Fosc (4.5)

TIMING WAVEFORMS:

KEY SBT and MP3 Trigger Mode:

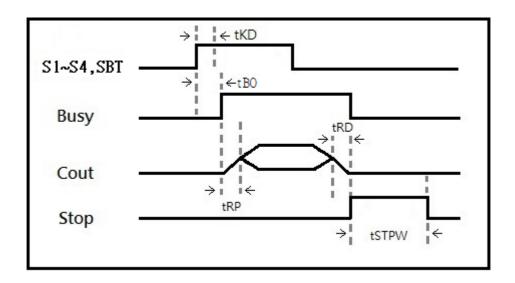


Fig. 24

CPU Parallel Mode:

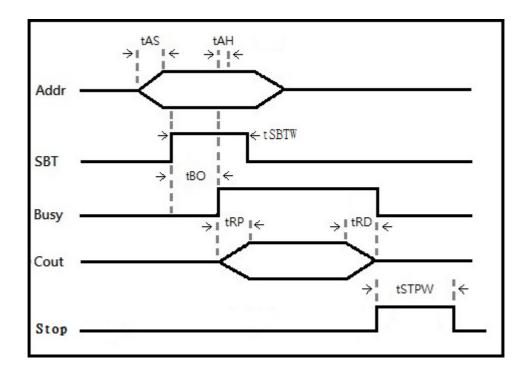


Fig.25

SPI Mode:

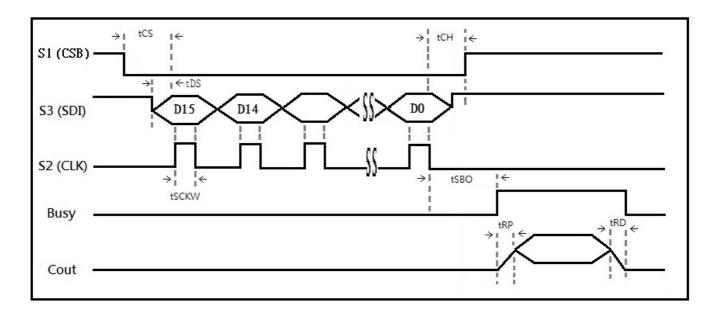


Fig. 26

I2C Mode:

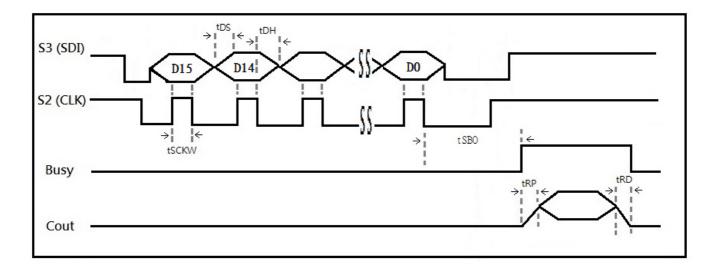
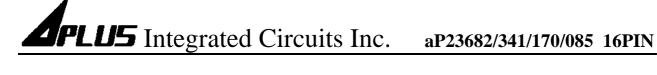


Fig. 27



AC CHARACTERISTICS ($T_A = 0$ to 70° C, $V_{DD} = 3.3$ V, $V_{SS} = 0$ V, 8KHz sampling)

Parameter	Min.	Typ.	Max.	Unit	Note
Key trigger debounce time (long)	_	16	_	ms	1
Key trigger debounce time (long) – Retrigger during voice playback.	_	24	_	ms	1
Key trigger debounce time (short)	_	1	_	ms	1
Key trigger debounce time (short) – Retrigger during voice playback.	_	1.5	_	ms	1
STOP pulse width (long)	_	128	_	ms	1
STOP pulse width (short)	_	500	_	μs	1
Address set-up time	300		_	ns	
Address hold time	300	_	_	ns	
SBT stroke pulse width (long)	16	_	_	ms	1
SBT stroke pulse width (short)	1	_	_	ms	1
BUSY signal output delay time(long)	_	24	_	ms	1
BUSY signal output delay time(short)	_	1	_	ms	1
Chip select set-up time	100	_	_	ns	
Chip select hold time	100		_	ns	
Serial clock pulse width	1	_	_	μs	
Data set-up time	100	_	_	ns	
Data hold time	100	_	_	ns	
BUSY signal output delay time	_	_	2	ms	
Ramp Up time	_	160	_	ms	
Ramp Up time at cpu parallel mode	_	20	_	ms	
Ramp Down time	_	160		ms	
Ramp Down time at cpu parallel mode	_	20	_	ms	
Full signal output delay time	_		2	ms	
	Key trigger debounce time (long) Retrigger during voice playback. Key trigger debounce time (short) Key trigger debounce time (short) Retrigger during voice playback. STOP pulse width (long) STOP pulse width (short) Address set-up time Address hold time SBT stroke pulse width (long) SBT stroke pulse width (short) BUSY signal output delay time(long) BUSY signal output delay time(short) Chip select set-up time Chip select hold time Serial clock pulse width Data set-up time Data hold time BUSY signal output delay time Ramp Up time Ramp Up time Ramp Up time Ramp Down time Ramp Down time at cpu parallel mode	Key trigger debounce time (long)—Key trigger debounce time (long) – Retrigger during voice playback.—Key trigger debounce time (short)—Key trigger debounce time (short) – Retrigger during voice playback.—STOP pulse width (long)—STOP pulse width (short)—Address set-up time300Address hold time300SBT stroke pulse width (long)16SBT stroke pulse width (short)1BUSY signal output delay time(long)—Chip select set-up time100Chip select hold time100Serial clock pulse width1Data set-up time100Data hold time100BUSY signal output delay time—Ramp Up time—Ramp Up time—Ramp Up time at cpu parallel mode—Ramp Down time—Ramp Down time at cpu parallel mode—	Key trigger debounce time (long) — 16 Key trigger debounce time (long) — 24 Retrigger during voice playback. Key trigger debounce time (short) — 1 Key trigger debounce time (short) — 1.5 Retrigger during voice playback. STOP pulse width (long) — 128 STOP pulse width (short) — 500 Address set-up time 300 — Address hold time 300 — SBT stroke pulse width (long) 16 — SBT stroke pulse width (short) 1 — BUSY signal output delay time(long) — 24 BUSY signal output delay time(short) — 1 Chip select set-up time 100 — Chip select hold time 100 — Serial clock pulse width 1 — Data set-up time 100 — BUSY signal output delay time 100 — Ramp Up time 100 — Ramp Up time 100 — Ramp Up time 100 — Ramp Down time 1000 — 20 Ramp Down time 1000 — 20	Key trigger debounce time (long) — 16 — Key trigger debounce time (long) — 24 — Retrigger debounce time (short) — 1 — Key trigger debounce time (short) — 1.5 — Retrigger during voice playback. STOP pulse width (long) — 128 — STOP pulse width (short) — 500 — Address set-up time 300 — — Address hold time 300 — — SBT stroke pulse width (short) 1 — — SBT stroke pulse width (short) 1 — — BUSY signal output delay time(long) — 24 — BUSY signal output delay time(short) — 1 — Chip select set-up time 100 — — Chip select hold time 100 — — Serial clock pulse width 1 — — Data set-up time 100 — — BUSY signal output delay time 100 — — Ramp Up time 100 — — Ramp Up time 100 — — Ramp Up time 100 — — Ramp Down time 100 — —	Key trigger debounce time (long) — 16 — ms Key trigger debounce time (long) — 24 — ms Key trigger debounce time (short) — 1 — ms Key trigger debounce time (short) — 1.5 — ms Key trigger debounce time (short) — 1.5 — ms Key trigger debounce time (short) — 1.5 — ms STOP pulse width (long) — 128 — ms STOP pulse width (short) — 500 — µs Address set-up time 300 — ns Address hold time 300 — ms SBT stroke pulse width (long) 16 — ms SBT stroke pulse width (short) 1 — ms BUSY signal output delay time(long) — 24 — ms BUSY signal output delay time(short) — 1 — ms Chip select set-up time 100 — ns Chip select hold time 100 — ns Serial clock pulse width 1 — µs Data set-up time 100 — ns BUSY signal output delay time 100 — ms Serial clock pulse width — 100 — ms Ramp Up time 100 — ms Ramp Up time 100 — ms Ramp Up time 100 — ms Ramp Down time 100 — ms Ramp Down time at cpu parallel mode — 20 — ms

Notes:

The long or short debounce time is selectable as whole chip option during Voice Files Compiling.

In Circuit Program Applications:

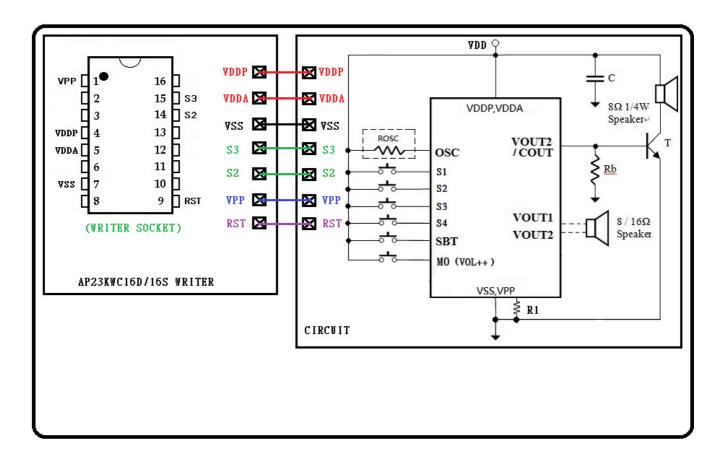


Fig. 28

- 1. Between VPP and GND should add R1(10K) Ω .
- 2. Between Writer and Circuit connect wire less than 10cm is the better

TYPICAL APPLICATIONS:

Key Mode

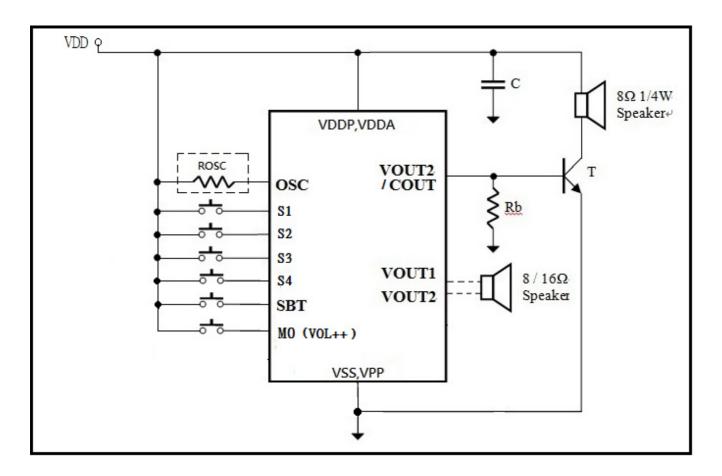


Fig. 29

Ex: Single key control volume.

If volume level is $8, 1 \rightarrow 2 \rightarrow 3 \rightarrow 4 \rightarrow 5 \rightarrow 6 \rightarrow 7 \rightarrow 8 \rightarrow 1 \rightarrow 2 \rightarrow 3 \rightarrow 4 \rightarrow \dots$

CPU Parallel Mode

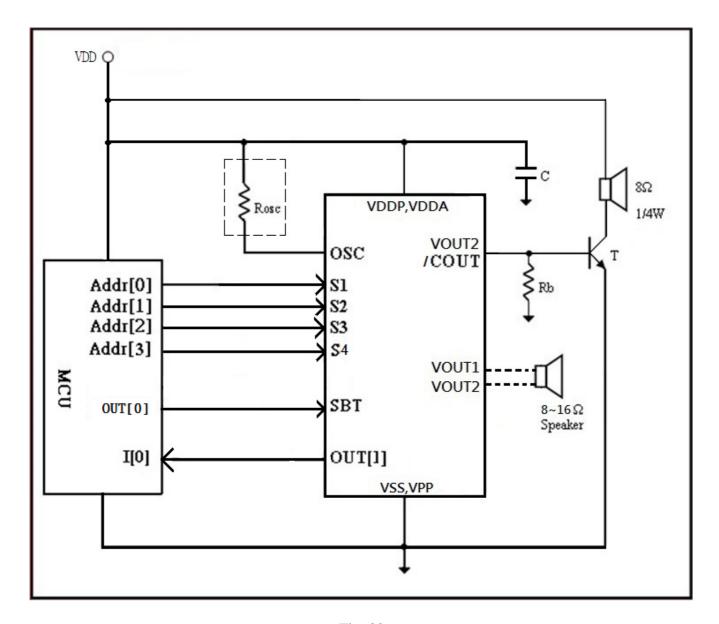


Fig. 30

Note:

- 1. C is capacitor from 0.1uF to 4.7uF depends on the kind of Vdd source and sound loudness.
- 2. Rb is base resistor from 120 Ohm to 390 Ohm depends on Vdd value and transistor gain.
- 3. T is an NPN transistor with beta larger than 150.
- 4. Reference value for the above components are Rb = 390 Ohm and T = 8050D.

SPI Mode

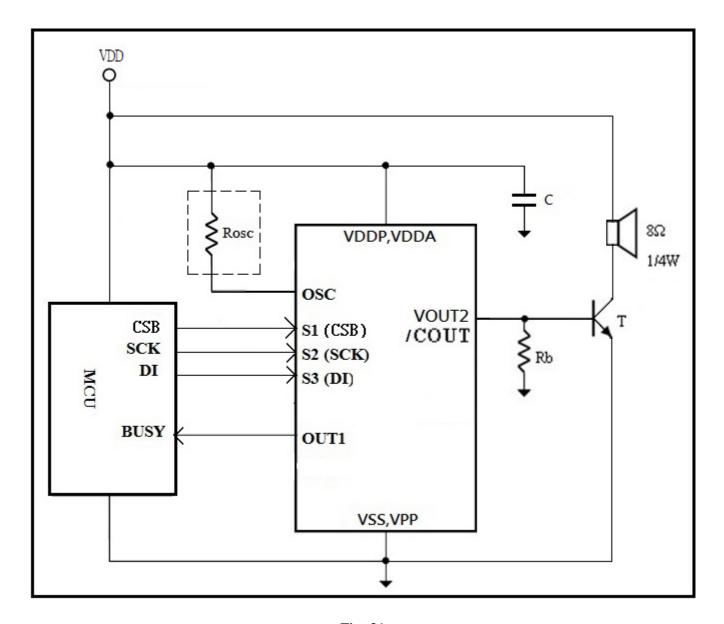


Fig. 31

I2C Mode

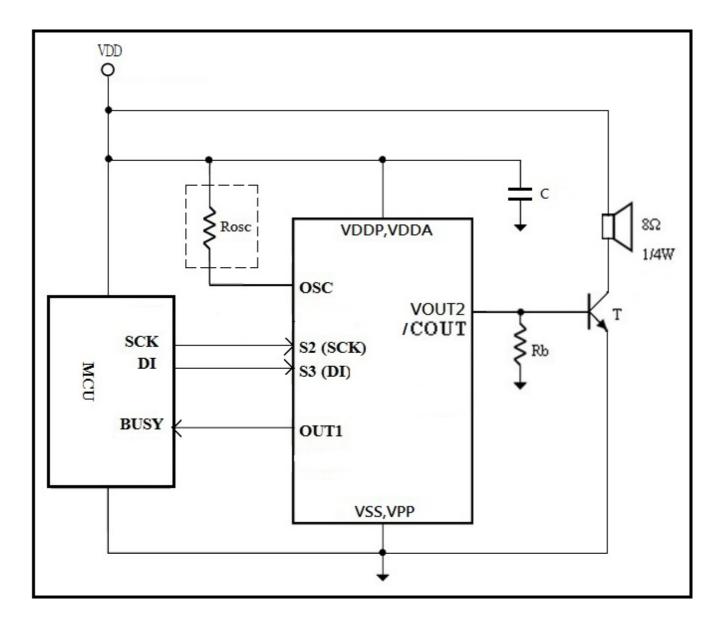


Fig. 32

MP3 Mode

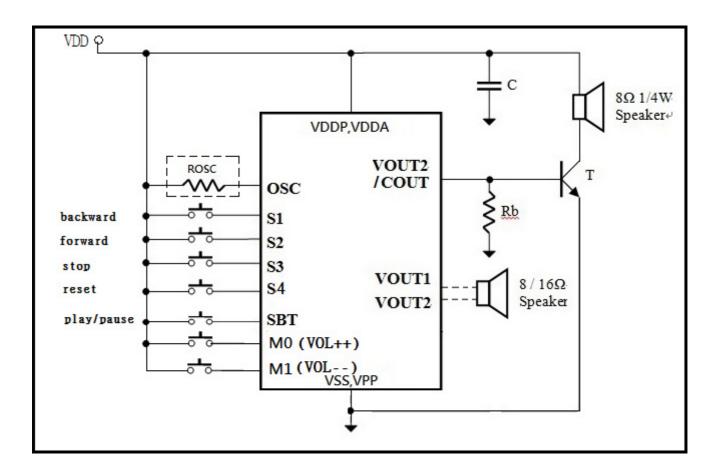
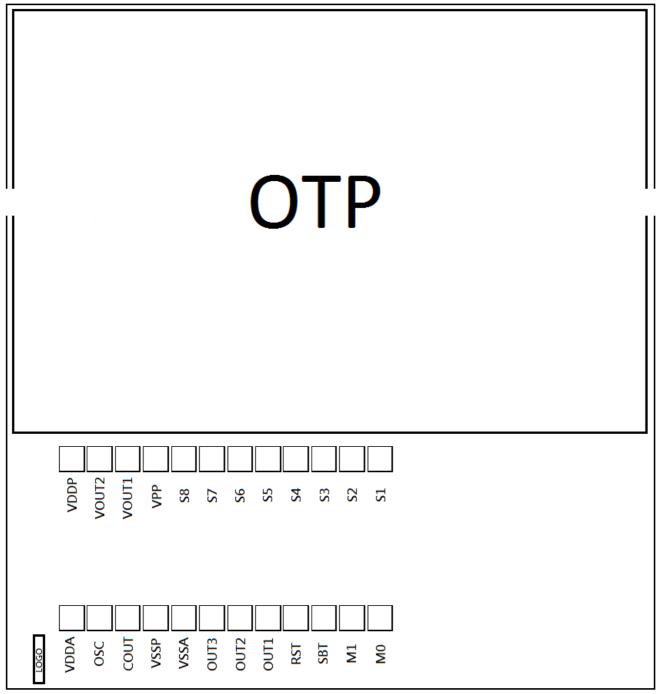


Fig. 33

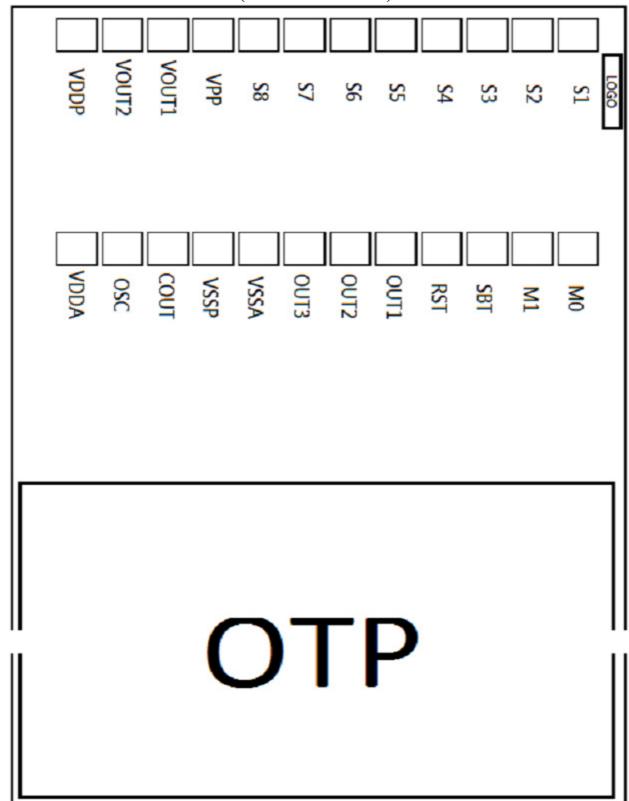
BONDING PAD DIAGRAMS (aP23682/aP23341)



Notes:

- Between VPP and GND should add $10K\Omega$.
- VDDA and VDDP should be connected to the Positive Power Supply.
- 3. VSSA and VSSP should be connected to the Power GND.
- 4. Substrate should be connected to the Power GND.

BONDING PAD DIAGRAMS (aP23170/aP23085)



Notes:

- 1.Between VPP and GND should add $10K\Omega$.
- 2.VDDA and VDDP should be connected to the Positive Power Supply.
- 3.VSSA and VSSP should be connected to the Power GND.
- 4. Substrate should be connected to the Power GND.

THERMAL

MAX

0.067

0.065

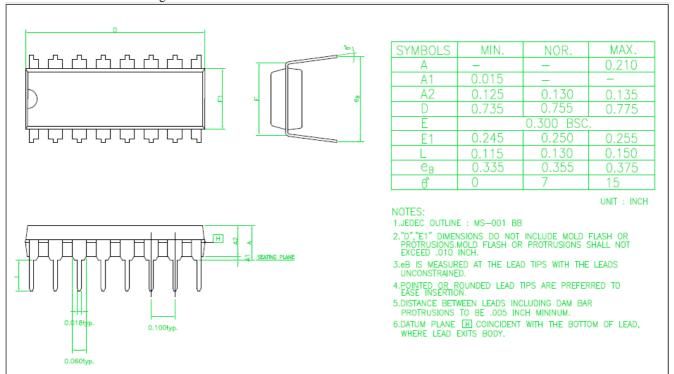
0.394

0.157

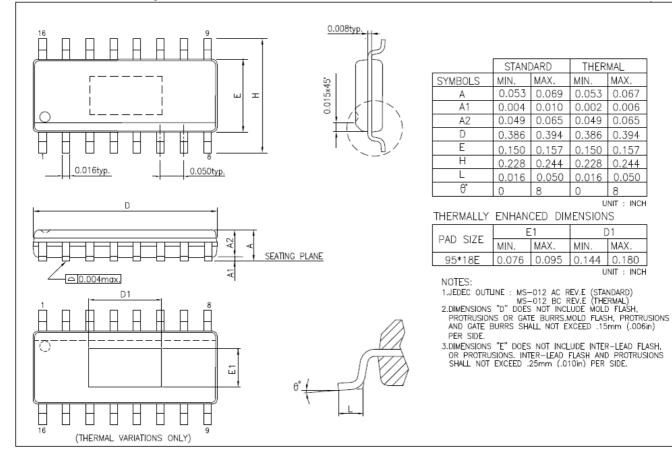
8 UNIT: INCH

PACKAGES DIMENSION OUTLINES

16-Pin 300mil P-DIP Package



16-Pin 150mil SOP Package



aP23682/341/170/085 16PIN

HISTORY

2015/07/20

aP23682_341__170_085 SPEC : Modify cpu control timing waveforms

Modify Page. 17 DC CHARACTERISTICS Reduce output function from 14 to 9.

2015/09/08

aP23682_341__170_085 SPEC: Modify ULAW5 to ULAW8

Add SBT mode independent description.

Optimize the CPU mode control.

Add In Circuit Program application on page. 29.